N-Channel Enhancement-Mode Vertical DMOS FET

## Features

- Low threshold (2.0V max.)
- High input impedance
- Low input capacitance (125pF max.)
- Fast switching speeds
- Low on-resistance
- Free from secondary breakdown
- Low input and output leakage
- Complementary N - and P-channel devices


## Applications

- Logic level interfaces - ideal for TTL and CMOS
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers
- Telecom switches


## General Description

This low threshold, enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

## Ordering Information

| Device | Package Options |  |  | $\mathrm{BV}_{\mathrm{DSs}} / \mathrm{BV}_{\mathrm{DGs}}$ <br> (V) | $\mathrm{R}_{\mathrm{DS}(\mathrm{ON})}$ (max) ( $\Omega$ ) | $I_{D(O N)}$ (min) (A) | $\begin{gathered} \mathbf{V}_{\mathrm{GS}(\mathrm{th})} \\ (\max ) \\ (\mathrm{V}) \end{gathered}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | TO-92 | TO-243AA (SOT-89) | Die* |  |  |  |  |
| TN2540 | TN2540N3-G | TN2540N8-G | TN2540ND | 400 | 12 | 1.0 | 2.0 |

-G indicates package is RoHS compliant ('Green')

* MIL visual screening available



## Absolute Maximum Ratings

| Parameter | Value |
| :--- | ---: |
| Drain-to-source voltage | $\mathrm{BV}_{\text {DSS }}$ |
| Drain-to-gate voltage | $\mathrm{BV}_{\text {DGS }}$ |
| Gate-to-source voltage | $\pm 20 \mathrm{~V}$ |
| Operating and storage temperature | $-55^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| Soldering temperature* | $300^{\circ} \mathrm{C}$ |

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

* Distance of 1.6 mm from case for 10 seconds.

Pin Configurations


TO-92 (N3)
TO-243AA (SOT-89) (N8)

## Product Marking

$Y Y=$ Year Sealed WW = Week Sealed
___ = "Green" Packaging
TO-92 (N3)
TN5DW
W = Code for week sealed
$\qquad$ = "Green" Packaging

## Thermal Characteristics

| Package |  | $\underset{\text { (pulsed) }}{\mathrm{I}_{\mathrm{D}}}$ <br> (A) | Power Dissipation $@ T_{A}=25^{\circ} \mathrm{C}$ <br> (W) | $\begin{gathered} \theta_{j c} \\ \left({ }^{\circ} \mathrm{C} / \mathrm{W}\right) \end{gathered}$ | $\begin{gathered} \boldsymbol{\theta}_{j a} \\ \left({ }^{\circ} \mathbf{C} / \mathbf{W}\right) \end{gathered}$ | $\begin{aligned} & \mathrm{I}_{\mathrm{DR}}{ }^{2} \\ & (\mathrm{~mA}) \end{aligned}$ | $I_{\text {DRM }}$ <br> (A) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| TO-92 | 175 | 2.0 | 0.74 | 125 | 170 | 175 | 2.0 |
| TO-243AA (SOT-89) | 260 | 1.8 | $1.6{ }^{\ddagger}$ | 15 | $78^{ \pm}$ | 260 | 1.8 |

## Notes:

$\dagger I_{D}$ (continuous) is limited by max rated $T_{j}$
$\ddagger$ Mounted on FR5 Board, $25 \mathrm{~mm} \times 25 \mathrm{~mm} \times 1.57 \mathrm{~mm}$.
Electrical Characteristics $\left(T_{A}=25^{\circ} \mathrm{C}\right.$ unless otherwise specified)

| Sym | Parameter | Min | Typ | Max | Units | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $B V_{\text {DSs }}$ | Drain-to-source breakdown voltage | 400 | - | - | V | $\mathrm{V}_{\text {GS }}=0 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mu \mathrm{~A}$ |
| $V_{\text {GS(th) }}$ | Gate threshold voltage | 0.6 | - | 2.0 | V | $V_{G S}=V_{D S}, I_{D}=1.0 \mathrm{~mA}$ |
| $\Delta \mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ | Change in $\mathrm{V}_{\text {GS(th) }}$ with temperature | - | -2.5 | -4.0 | $\mathrm{mV} /{ }^{\circ} \mathrm{C}$ | $V_{G S}=V_{D S}, I_{D}=1.0 \mathrm{~mA}$ |
| $\mathrm{l}_{\text {Gss }}$ | Gate body leakage | - | - | 100 | nA | $V_{G S}= \pm 20 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=0 \mathrm{~V}$ |
| $\mathrm{I}_{\text {Dss }}$ | Zero gate voltage drain current | - | - | 10 | $\mu \mathrm{A}$ | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=$ Max Rating |
|  |  | - | - | 1.0 | mA | $\begin{aligned} & V_{\text {DS }}=0.8 \text { Max Rating, } \\ & V_{G S}=0 \mathrm{~V}, \mathrm{~T}_{A}=125^{\circ} \mathrm{C} \end{aligned}$ |
| $\mathrm{I}_{\mathrm{DO} \text { ( })}$ | On-state drain current | 0.3 | 0.5 | - | A | $\mathrm{V}_{\mathrm{GS}}=4.5 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=25 \mathrm{~V}$ |
|  |  | 0.75 | 1.0 | - |  | $\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{~V}_{\mathrm{DS}}=25 \mathrm{~V}$ |
| $\mathrm{R}_{\text {DS(ON) }}$ | Static drain-to-source on-state resistance | - | 8.0 | 12 | $\Omega$ | $\mathrm{V}_{G S}=4.5 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=150 \mathrm{~mA}$ |
|  |  | - | 8.0 | 12 |  | $\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=500 \mathrm{~mA}$ |
| $\Delta \mathrm{R}_{\text {DS(ON })}$ | Change in $\mathrm{R}_{\mathrm{DS}(\text { ON })}$ with temperature | - | - | 0.75 | \%/ ${ }^{\circ} \mathrm{C}$ | $\mathrm{V}_{G S}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=500 \mathrm{~mA}$ |
| $\mathrm{G}_{\text {FS }}$ | Forward transductance | 125 | 200 | - | mmho | $\mathrm{V}_{\mathrm{DS}}=25 \mathrm{~V}, \mathrm{I}_{\mathrm{D}}=100 \mathrm{~mA}$ |
| $\mathrm{C}_{\text {ISS }}$ | Input capacitance | - | 95 | 125 | pF | $\begin{aligned} & V_{G S}=0 \mathrm{~V}, \\ & V_{D S}=25 \mathrm{~V}, \\ & f=1.0 \mathrm{MHz} \end{aligned}$ |
| $\mathrm{C}_{\text {oss }}$ | Common source output capacitance | - | 20 | 70 |  |  |
| $\mathrm{C}_{\text {RSS }}$ | Reverse transfer capacitance | - | 10 | 25 |  |  |
| $\mathrm{t}_{\mathrm{d}(\mathrm{ON})}$ | Turn-on delay time | - | - | 20 | ns | $\begin{aligned} & V_{\mathrm{DD}}=25 \mathrm{~V}, \\ & \mathrm{I}_{\mathrm{D}}=1.0 \mathrm{~A}, \\ & \mathrm{R}_{\mathrm{GEN}}=25 \Omega \end{aligned}$ |
| $\mathrm{t}_{\mathrm{r}}$ | Rise time | - | - | 15 |  |  |
| $\mathrm{t}_{\text {d(OFF) }}$ | Turn-off delay time | - | - | 25 |  |  |
| $\mathrm{t}_{\mathrm{f}}$ | Fall time | - | - | 20 |  |  |
| $\mathrm{V}_{\text {SD }}$ | Diode forward voltage drop | - | - | 1.8 | V | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{I}_{\text {SD }}=200 \mathrm{~mA}$ |
| $\mathrm{t}_{\text {t }}$ | Reverse recovery time | - | 300 | - | ns | $\mathrm{V}_{\mathrm{GS}}=0 \mathrm{~V}, \mathrm{I}_{\mathrm{SD}}=1.0 \mathrm{~A}$ |

## Notes:

1. All D.C. parameters $100 \%$ tested at $25^{\circ} \mathrm{C}$ unless otherwise stated. (Pulse test: $300 \mu \mathrm{~s}$ pulse, $2 \%$ duty cycle.)
2. All A.C. parameters sample tested.

## Switching Waveforms and Test Circuit



## Typical Performance Curves



Transconductance vs. Drain Current



Saturation Characteristics


Power Dissipation vs. Ambient Temperature


Thermal Response Characteristics


## Typical Performance Curves (cont.)



Transfer Characteristics


Capacitance vs. Drain-to-Source Voltage




Gate Drive Dynamic Characteristics


## 3-Lead TO-92 Package Outline (N3)



Front View


Side View


Bottom View

| Symbol |  | A | b | c | D | E | E1 | e | e1 | L |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dimensions (inches) | MIN | . 170 | . $014{ }^{+}$ | . $014{ }^{+}$ | . 175 | . 125 | . 080 | . 095 | . 045 | . 500 |
|  | NOM | - | - | - | - | - | - | - | - | - |
|  | MAX | . 210 | .022 ${ }^{+}$ | .022 ${ }^{+}$ | . 205 | . 165 | . 105 | . 105 | . 055 | .610* |

[^0]
## 3-Lead TO-243AA (SOT-89) Package Outline (N8)



Top View


Side View

| Symbol |  | A | b | b1 | C | D | D1 | E | E1 | e | e1 | H | L |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dimensions (mm) | MIN | 1.40 | 0.44 | 0.36 | 0.35 | 4.40 | 1.62 | 2.29 | 2.13 | $\begin{aligned} & 1.50 \\ & \text { BSC } \end{aligned}$ | $\begin{aligned} & 3.00 \\ & \text { BSC } \end{aligned}$ | 3.94 | 0.89 |
|  | NOM | - | - | - | - | - | - | - | - |  |  | - | - |
|  | MAX | 1.60 | 0.56 | 0.48 | 0.44 | 4.60 | 1.83 | 2.60 | 2.29 |  |  | 4.25 | 1.20 |

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.
Drawings not to scale.
Supertex Doc. \#: DSPD-3TO243AAN8, Version D070908.
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

[^1]
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[^0]:    JEDEC Registration TO-92.

    * This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.
    $\dagger$ This dimension is a non-JEDEC dimension.
    Drawings not to scale.
    Supertex Doc.\#: DSPD-3TO92N3, Version D080408.

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